



Material Content Data Sheet

Sales Product Name	TLE6714G			Issued		28. August 2013		
MA#	MA000043159							
Package	P-DSO-28-17			Weight*		815.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.056	2.34	2.34	23354	23354
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		88	
	non noble metal	zinc	7440-66-6	0.288	0.04		353	
	non noble metal	iron	7439-89-6	5.754	0.71		7052	
	non noble metal	copper	7440-50-8	233.637	28.63	29.39	286335	293828
wire	noble metal	gold	7440-57-5	1.498	0.18	0.18	1836	1836
encapsulation	plastics	brominated resin	-	5.492	0.67		6731	
	organic material	carbon black	1333-86-4	5.492	0.67		6731	
	inorganic material	antimonytrioxide	1309-64-4	11.533	1.41		14135	
	plastics	epoxy resin	-	59.864	7.34		73367	
	inorganic material	silicondioxide	60676-86-0	466.830	57.21	67.30	572123	673088
leadfinish	non noble metal	tin	7440-31-5	0.983	0.12		1204	
	non noble metal	lead	7439-92-1	1.548	0.19	0.31	1897	3101
plating	noble metal	silver	7440-22-4	0.678	0.08	0.08	830	830
glue	plastics	epoxy resin	-	0.647	0.08		793	
	noble metal	silver	7440-22-4	2.587	0.32	0.40	3171	3963
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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